



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSS315P H6327	Issued	11. May 2021
MA#	MA001636970		
Package	PG-SOT23-3-5	Weight*	9.38 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		470	
	noble metal	gold	7440-57-5	0.017	0.18		1823	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20659	22952
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	chromium	7440-47-3	0.009	0.10		963	
	non noble metal	copper	7440-50-8	3.000	31.97	32.11	319742	321090
wire	non noble metal	copper	7440-50-8	0.045	0.48	0.48	4774	4774
encapsulation	organic material	carbon black	1333-86-4	0.057	0.60		6049	
	plastics	epoxy resin	-	1.220	13.01		130059	
	inorganic material	silicondioxide	60676-86-0	4.399	46.88	60.49	468819	604927
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15947	15947
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30310	30310
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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